ABSOCIATION CONNECTING LECTRONICS INDUSTRIES	PC. Bannockt	ourn. Illinois. A	Il rights reserved ur ntions.	nder both	This docum level parts,	ent is a declaration the declaration en	n of the substar compasses all l	ces within the manufactu ower level materials for w	rer listed i which the r	tem. Note: if nanufacturer	the item is an as has engineering	sembly with lower responsibility.	
	IPC Web Site for Information on IPC-1752 Standard Form http://www.ipc.org/IPC-175x Distr				e * Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Materials and Mfg				fg Informatio	on			
Supplier Information													
Company name* Company t			/ unique ID			Unique ID Authority				Response Date*			
On Semiconductor										2021-02-04			
Contact Name Title - Contact			lact			Phone - Contact*				Email - Contact*			
Product-Env-Stewards Product Env			Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Authorized Representative* Title - Repre			resentative		Phone - Representative*			Email - Representative*					
Product-Env-Stewards Product E			oduct Enviro Compliance			NA			Product-Env-Stewards@onsemi.com				
Requester Item Number	Mfr Item	Number	Mfr Item Name			Effective Date	Version	Manufacturing Site		Weight*	UOM	Unit Type	
	FDMF67	/08N	DrMOS Module			2021-02-04		PBB		134.314	mg	Each	
Manufacturing Proccess Informa	tion								1				
Terminal Plating / Grid Array M	aterial Terminal Base A		Alloy J.	loy J-STD-020 MSL Rating		Peak Process Body Temperature M		ature Max Time at Peak	eak Temperature Number of Reflow Cycles		eles		
Matte Tin (Sn) - annealed CU Alloy			1			260	С	30	secor	ids 3			
Comments													
evel 1 - maximum time at peak temperati	ire during sol	dering is 10-3	0 seconds										
For more information regarding material	composition	please refer to	page 3										

RoHS Material Composition Declaration				Declaration Type *	Detailed
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		mium (Cr6+), Polybrominated Biphenyls (Pl		dmium and quantity limit of 0.1% by mass (10 minated Diphenyl Ethers (PBDE), and Bis(2-et	
cadmium, hexavalentchromium, polybromina contains a RoHS restricted substance inexces encompass all such components. Supplier cer as of the date that Supplier completes this for Company acknowledges that Supplier may h independently verified information provided certification in this paragraph. If the Company	ated biphenyls and/or polybrominated dip s of an applicable quantity limit, please in iffies that it gathered the information it pr m.Supplier acknowledges that Company ave relied on informationprovided by oth by others, Supplier agrees that, at a minir and the Supplier enter into a written agr esource of the Supplier's liability and the	henyl ethers (each a "RoHS restricted substa ndicate below which, if any, RoHS exemption ovides in this form using appropriate methoo will rely on this certification in determining ers in completing this form, and that Supplie num, itssuppliers have provided certification eement with respect to the identified part, the Company's remedies for issues that arise reg	nce") in exco n you believe ls to ensure i the compliar r may not ha s regarding t terms and co	e may apply. If the part is an assembly with low s accuracy and that such information is true an ce of its products with European Union member de independently verified such information. Ho neir contributions to the part, and those certifica	ove. If a homogeneous material within the part er level components, the declaration shall d correct to the best of its knowledge and belief, er state laws that implement the RoHS Directive. wever, in situations where Supplier has not ations are at least as comprehensive as the anty rights and/or remedies provided as part of
RoHS Declaration * 4 - Item(s) does not contain RoHS restricted subst	ances per the definition above except for sele	ected exempt	ions Supplier Acceptance	* Accepted
Exemption: 7a: Lead in high melting temp	erature type solders (i.e. lead based sol	der alloys containing 85% by weight or m	ore lead).		
Exemption List Version	EL-2011/534/EU				
Declaration Signature					
Instructions: Complete all of the required Requester) and click on Submit Form to h			e drop-dowi	a. This will display the signature area. Digita	lly sign the declaration (if required by the
Supplier Digital Signature	astislav Drska	Le			

Homogeneous Material Composition Declaration for Electronic Products

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight	Unit of Measure
Clip	19.6	mg	Supplier	Zinc (Zn)	7440-66-6		0.0235	mg
			Supplier	Iron (Fe)	7439-89-6		0.4704	mg
			Supplier	Copper (Cu)	7440-50-8		19.0904	mg
			Supplier	Phosphorus (P)	7723-14-0		0.0157	mg
Die	0.096	mg	Supplier	Silicon (Si)	7440-21-3		0.096	mg
Die Attach Solder	5.101	mg	Supplier	Silver (Ag)	7440-22-4		0.1275	mg
			А	Lead (Pb)	7439-92-1	7a	4.7184	mg
			Supplier	Tin (Sn)	7440-31-5		0.2551	mg
Lead Frame	44.201	mg	Supplier	Silver (Ag)	7440-22-4		0.054	mg
			Supplier	Zinc (Zn)	7440-66-6		0.049	mg
			Supplier	Iron (Fe)	7439-89-6		0.998	mg
			Supplier	Copper (Cu)	7440-50-8		43.1	mg
Mold Compound-Black	63.216	mg	Supplier	Ortho Cresol Novolac Resin	29690-82-2		3.79	mg
			Supplier	Carbon Black (C)	1333-86-4		0.316	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		56.9	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		2.21	mg
Plating	2.0	mg	Supplier	Tin (Sn)	7440-31-5		2	mg
Wire Bond - Au	0.1	mg	Supplier	Gold (Au)	7440-57-5		0.1	mg